

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s): SHIMOKAWA, et al.

2/A

Filed: October 9, 2001

Q.F.

For: PB-FREE SOLDER-CONNECTED STRUCTURE AND  
ELECTRONIC DEVICE

1D/  
25/01

**PRELIMINARY AMENDMENT**

Assistant Commissioner for Patents  
Washington, D.C. 20231

October 9, 2001

Sir:

Please amend the above-identified application, prior to examination  
thereof, as follows:

**IN THE SPECIFICATION**

Page 1, between the title and the heading "TECHNICAL FIELD", please  
add the following new paragraph:

This application is a Continuation application of prior application Serial  
No. 09/581,631, filed June 15, 2000, which is a national stage application under  
35 USC 371 of International (PCT) Application No. PCT/JP98/05565, filed  
December 9, 1998